



PSMN2R0-30YLD

N-channel 30 V, 2.0 mΩ logic level MOSFET in LPAK56 using NextPowerS3 Technology

25 October 2018

Product data sheet

1. General description

Logic level gate drive N-channel enhancement mode MOSFET in LPAK56 package. NextPowerS3 portfolio utilising NXP's unique "SchottkyPlus" technology delivers high efficiency, low spiking performance usually associated with MOSFETs with an integrated Schottky or Schottky-like diode but without problematic high leakage current. NextPowerS3 is particularly suited to high efficiency applications at high switching frequencies.

2. Features and benefits

- Ultra low Q_G , Q_{GD} and Q_{OSS} for high system efficiency, especially at higher switching frequencies
- Superfast switching with soft-recovery; s-factor > 1
- Low spiking and ringing for low EMI designs
- Unique "SchottkyPlus" technology; Schottky-like performance with < 1 µA leakage at 25 °C
- Optimised for 4.5 V gate drive
- Low parasitic inductance and resistance
- High reliability clip bonded and solder die attach Power SO8 package; no glue, no wire bonds, qualified to 175 °C
- Wave solderable; exposed leads for optimal visual solder inspection

3. Applications

- On-board DC-to-DC solutions for server and telecommunications
- Secondary-side synchronous rectification in telecommunication applications
- Voltage regulator modules (VRM)
- Point-of-Load (POL) modules
- Power delivery for V-core, ASIC, DDR, GPU, VGA and system components
- Brushed and brushless motor control

4. Quick reference data

Table 1. Quick reference data

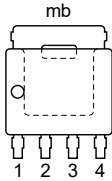
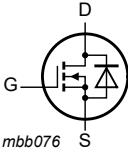
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C		-	-	30	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; Fig. 2	[1]	-	-	100	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; Fig. 1		-	-	142	W
T _j	junction temperature			-55	-	175	°C
Static characteristics							
R _{DSon}	drain-source on-state resistance	V _{GS} = 4.5 V; I _D = 25 A; T _j = 25 °C; Fig. 10		-	2.1	2.5	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; Fig. 10		-	1.61	2	mΩ
Dynamic characteristics							

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Q_{GD}	gate-drain charge	$I_D = 25\text{ A}$; $V_{DS} = 15\text{ V}$; $V_{GS} = 4.5\text{ V}$; Fig. 12 ; Fig. 13	-	6.3	-	nC
$Q_{G(tot)}$	total gate charge		-	21.8	-	nC
Source-drain diode						
S	softness factor	$I_S = 25\text{ A}$; $di_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$; $V_{DS} = 15\text{ V}$; Fig. 16	-	1.02	-	

[1] Continuous current is limited by package.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 LPAK56; Power-SO8 (SOT669)	 mbb076
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN2R0-30YLD	LPAK56; Power-SO8	Plastic single-ended surface-mounted package (LPAK56; Power-SO8); 4 leads	SOT669

7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN2R0-30YLD	2D030L

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	30	V
V_{DGR}	drain-gate voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$	-	30	V
V_{GS}	gate-source voltage		-20	20	V
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; Fig. 1	-	142	W
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; Fig. 2	[1]	100	A
		$V_{GS} = 10\text{ V}$; $T_{mb} = 100\text{ °C}$; Fig. 2	[1]	100	A
I_{DM}	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ °C}$; Fig. 3	-	793	A

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Symbol	Parameter	Conditions		Min	Max	Unit
T_{stg}	storage temperature			-55	175	°C
T_j	junction temperature			-55	175	°C
$T_{\text{slid(M)}}$	peak soldering temperature			-	260	°C
V_{ESD}	electrostatic discharge voltage	HBM		1000	-	V
Source-drain diode						
I_S	source current	$T_{\text{mb}} = 25\text{ °C}$	[1]	-	100	A
I_{SM}	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{\text{mb}} = 25\text{ °C}$		-	793	A
Avalanche ruggedness						
$E_{\text{DS(AL)S}}$	non-repetitive drain-source avalanche energy	$I_D = 25\text{ A}$; $V_{\text{sup}} \leq 30\text{ V}$; $R_{\text{GS}} = 50\text{ }\Omega$; $V_{\text{GS}} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ °C}$; unclamped; $t_p = 815\text{ }\mu\text{s}$	[2]	-	397	mJ

[1] Continuous current is limited by package.

[2] Protected by 100% test

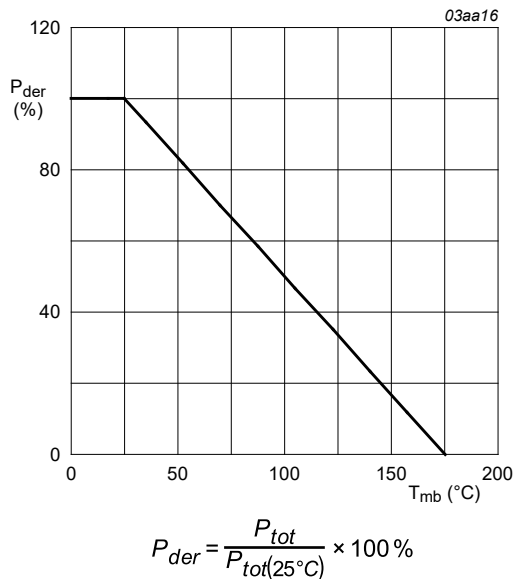


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

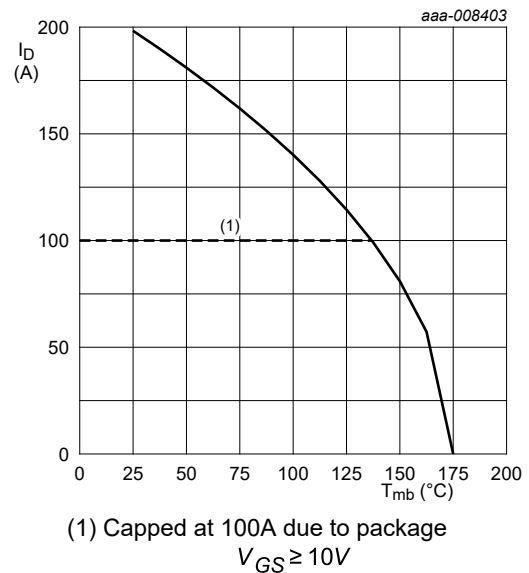
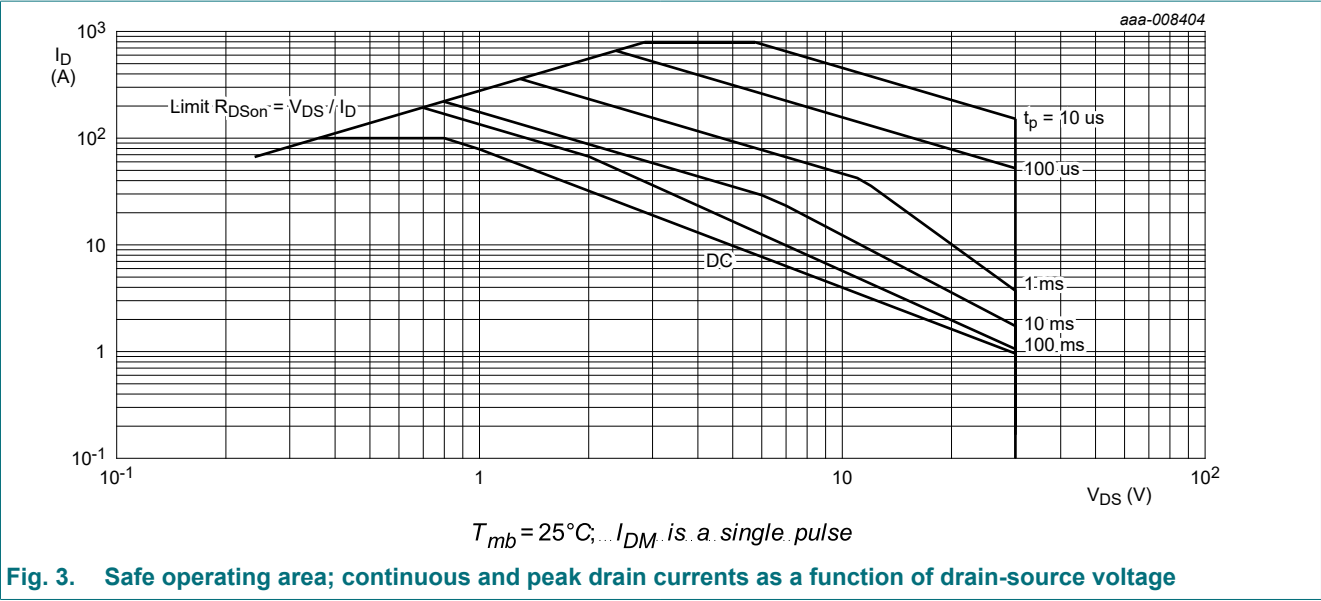


Fig. 2. Continuous drain current as a function of mounting base temperature



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4	-	0.92	1.06	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Fig. 5	-	50	-	K/W
		Fig. 6	-	125	-	K/W

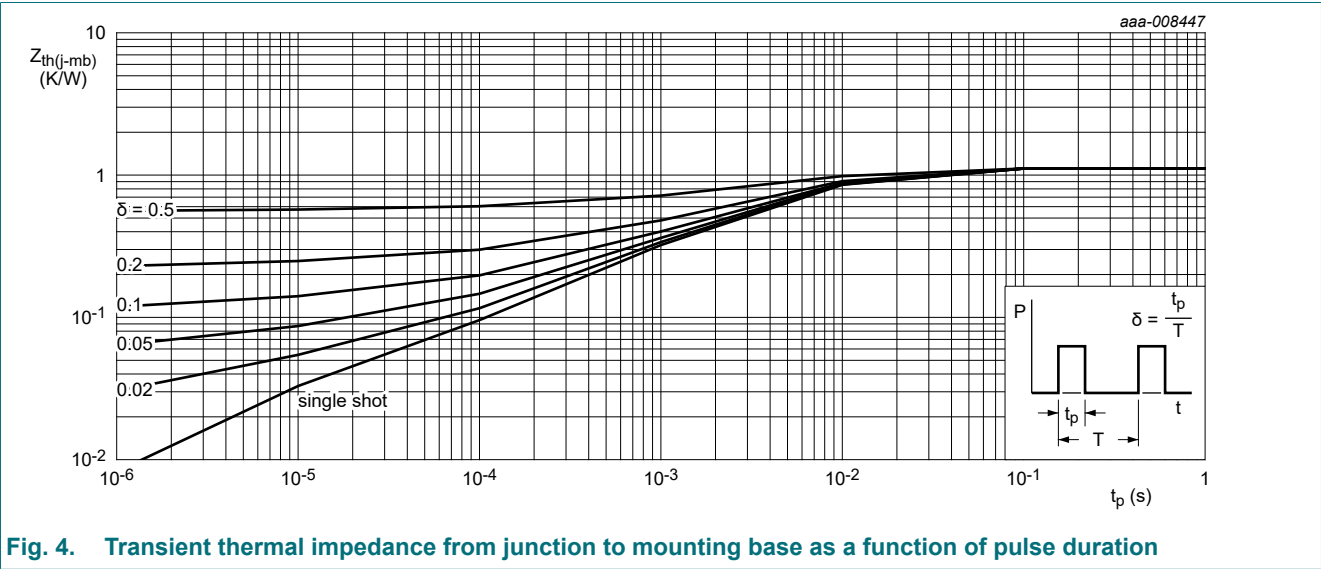


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

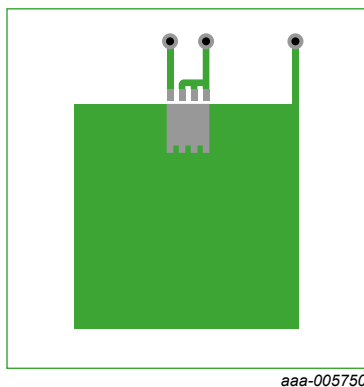


Fig. 5. PCB layout for thermal resistance junction to ambient 1" square pad; FR4 Board; 2oz copper

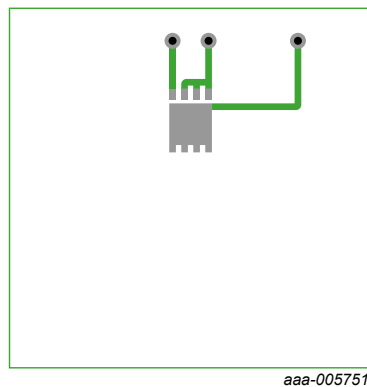


Fig. 6. PCB layout for thermal resistance junction to ambient minimum footprint; FR4 board; 2oz copper

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 ^\circ C$	30	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 ^\circ C$	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 ^\circ C$	1.2	1.7	2.2	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	$25 ^\circ C \leq T_j \leq 150 ^\circ C$	-	-4.4	-	mV/K
I_{DSS}	drain leakage current	$V_{DS} = 24 V; V_{GS} = 0 V; T_j = 25 ^\circ C$	-	-	1	μA
		$V_{DS} = 24 V; V_{GS} = 0 V; T_j = 125 ^\circ C$	-	1.7	-	μA
I_{GSS}	gate leakage current	$V_{GS} = 16 V; V_{DS} = 0 V; T_j = 25 ^\circ C$	-	-	100	nA
		$V_{GS} = -16 V; V_{DS} = 0 V; T_j = 25 ^\circ C$	-	-	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5 V; I_D = 25 A; T_j = 25 ^\circ C;$ Fig. 10	-	2.1	2.5	mΩ
		$V_{GS} = 4.5 V; I_D = 25 A; T_j = 150 ^\circ C;$ Fig. 10; Fig. 11	-	-	4.2	mΩ
		$V_{GS} = 10 V; I_D = 25 A; T_j = 25 ^\circ C;$ Fig. 10	-	1.61	2	mΩ
		$V_{GS} = 10 V; I_D = 25 A; T_j = 150 ^\circ C;$ Fig. 10; Fig. 11	-	-	3.3	mΩ
R_G	gate resistance	$f = 1 MHz$	-	0.9	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 25 A; V_{DS} = 15 V; V_{GS} = 10 V;$ Fig. 12; Fig. 13	-	46	-	nC
		$I_D = 25 A; V_{DS} = 15 V; V_{GS} = 4.5 V;$ Fig. 12; Fig. 13	-	21.8	-	nC
		$I_D = 0 A; V_{DS} = 0 V; V_{GS} = 10 V$	-	41.5	-	nC
Q_{GS}	gate-source charge	$I_D = 25 A; V_{DS} = 15 V; V_{GS} = 4.5 V;$ Fig. 12; Fig. 13	-	6.8	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	4.5	-	nC

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$Q_{GS(th-pl)}$	post-threshold gate-source charge			-	2.3	-	nC
Q_{GD}	gate-drain charge			-	6.3	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 25\text{ A}$; $V_{DS} = 15\text{ V}$; Fig. 12 ; Fig. 13		-	2.5	-	V
C_{iss}	input capacitance	$V_{DS} = 15\text{ V}$; $V_{GS} = 0\text{ V}$; $f = 1\text{ MHz}$;		-	2969	4157	pF
C_{oss}	output capacitance	$T_j = 25\text{ }^{\circ}\text{C}$; Fig. 14		-	1477	2068	pF
C_{rss}	reverse transfer capacitance			-	206	453	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15\text{ V}$; $R_L = 0.6\text{ }\Omega$; $V_{GS} = 4.5\text{ V}$; $R_{G(ext)} = 5\text{ }\Omega$		-	19	-	ns
t_r	rise time			-	31	-	ns
$t_{d(off)}$	turn-off delay time			-	24	-	ns
t_f	fall time			-	19	-	ns
Q_{oss}	output charge	$V_{GS} = 0\text{ V}$; $V_{DS} = 15\text{ V}$; $f = 1\text{ MHz}$; $T_j = 25\text{ }^{\circ}\text{C}$		-	31.6	-	nC
Source-drain diode							
V_{SD}	source-drain voltage	$I_S = 25\text{ A}$; $V_{GS} = 0\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 15		-	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 25\text{ A}$; $dI_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$; $V_{DS} = 15\text{ V}$; Fig. 16		-	37.5	-	ns
Q_r	recovered charge		[1]	-	32	-	nC
t_a	reverse recovery rise time			-	18.6	-	ns
t_b	reverse recovery fall time			-	18.9	-	ns
S	softness factor			-	1.02	-	

[1] includes capacitive recovery

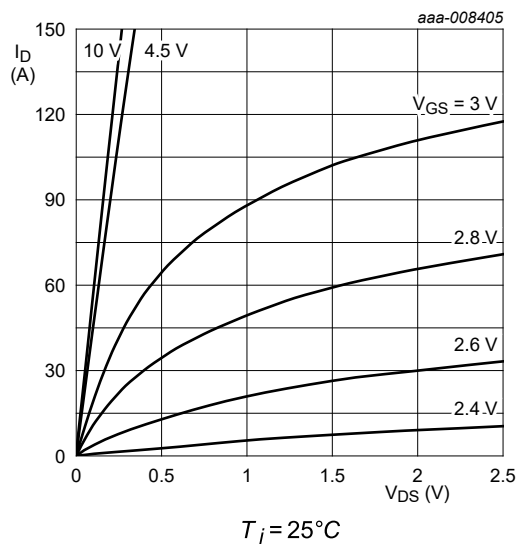


Fig. 7. Output characteristics; drain current as a function of drain-source voltage; typical values

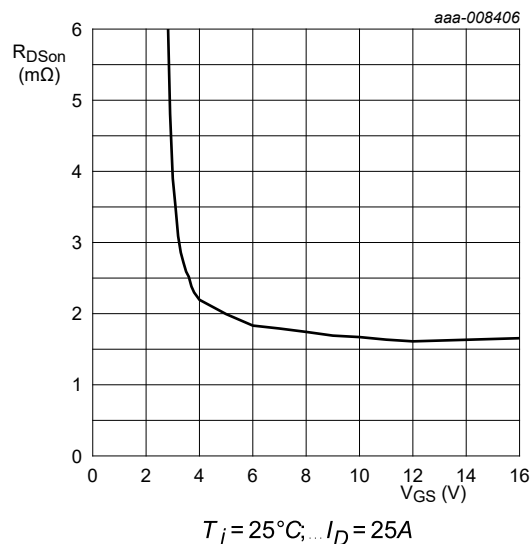


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

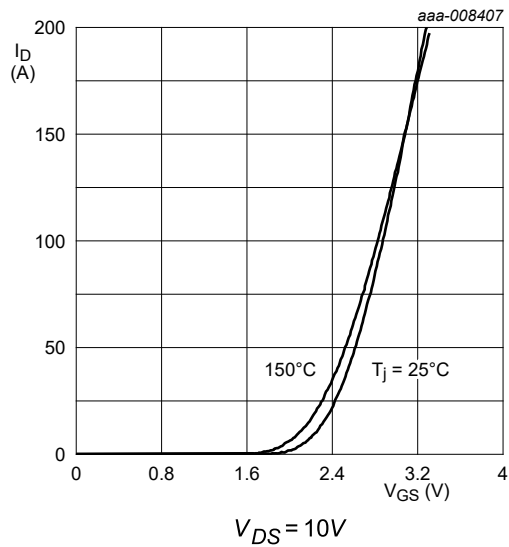


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

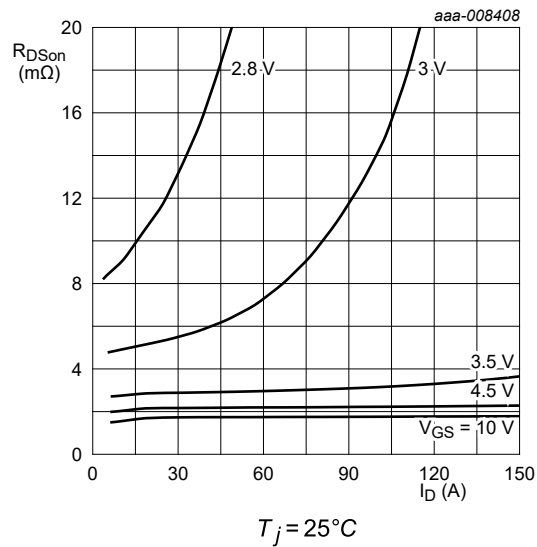


Fig. 10. Drain-source on-state resistance as a function of drain current; typical values

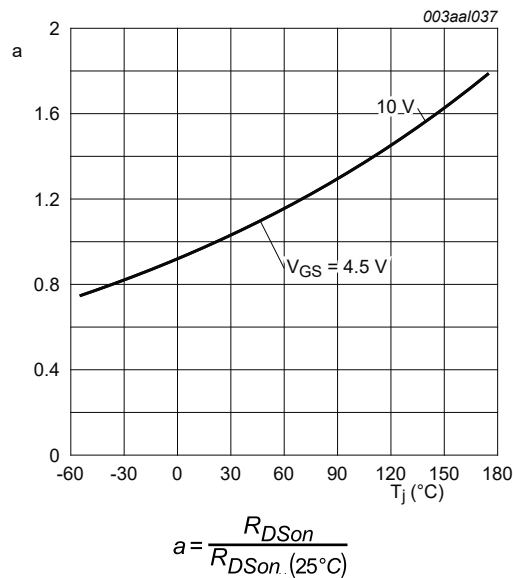


Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature

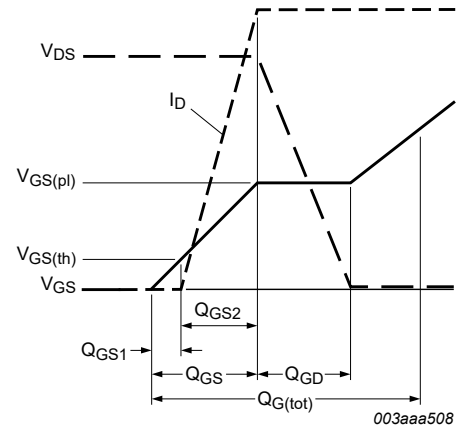


Fig. 12. Gate charge waveform definitions

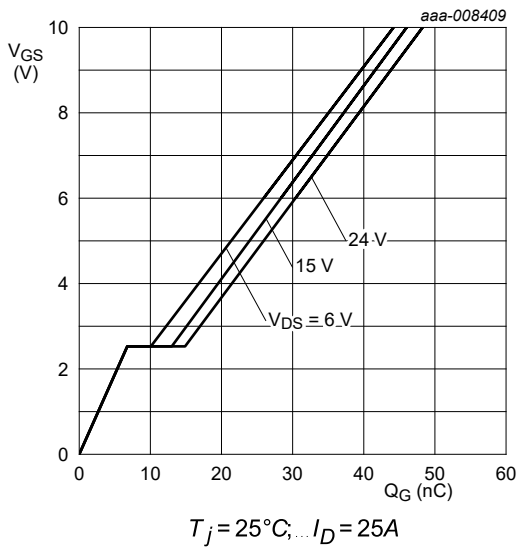


Fig. 13. Gate-source voltage as a function of gate charge; typical values

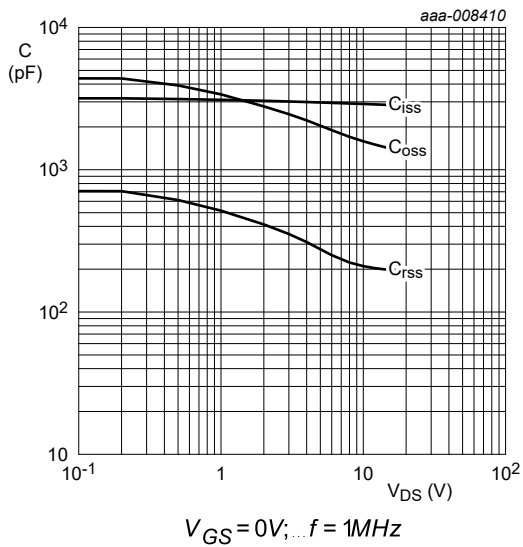


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

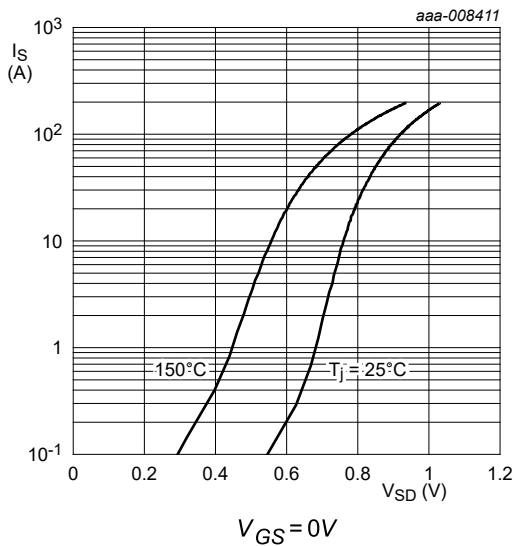


Fig. 15. Source current as a function of source-drain voltage; typical values

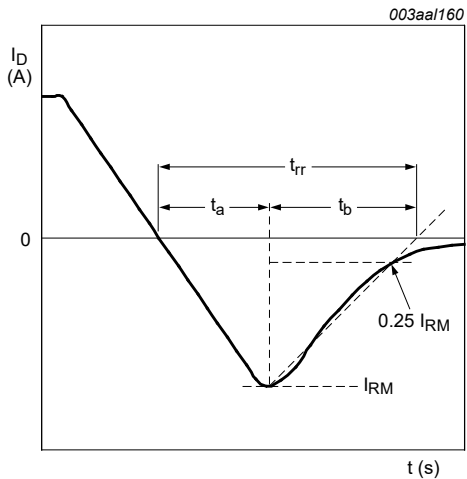


Fig. 16. Reverse recovery timing definition

11. Package outline

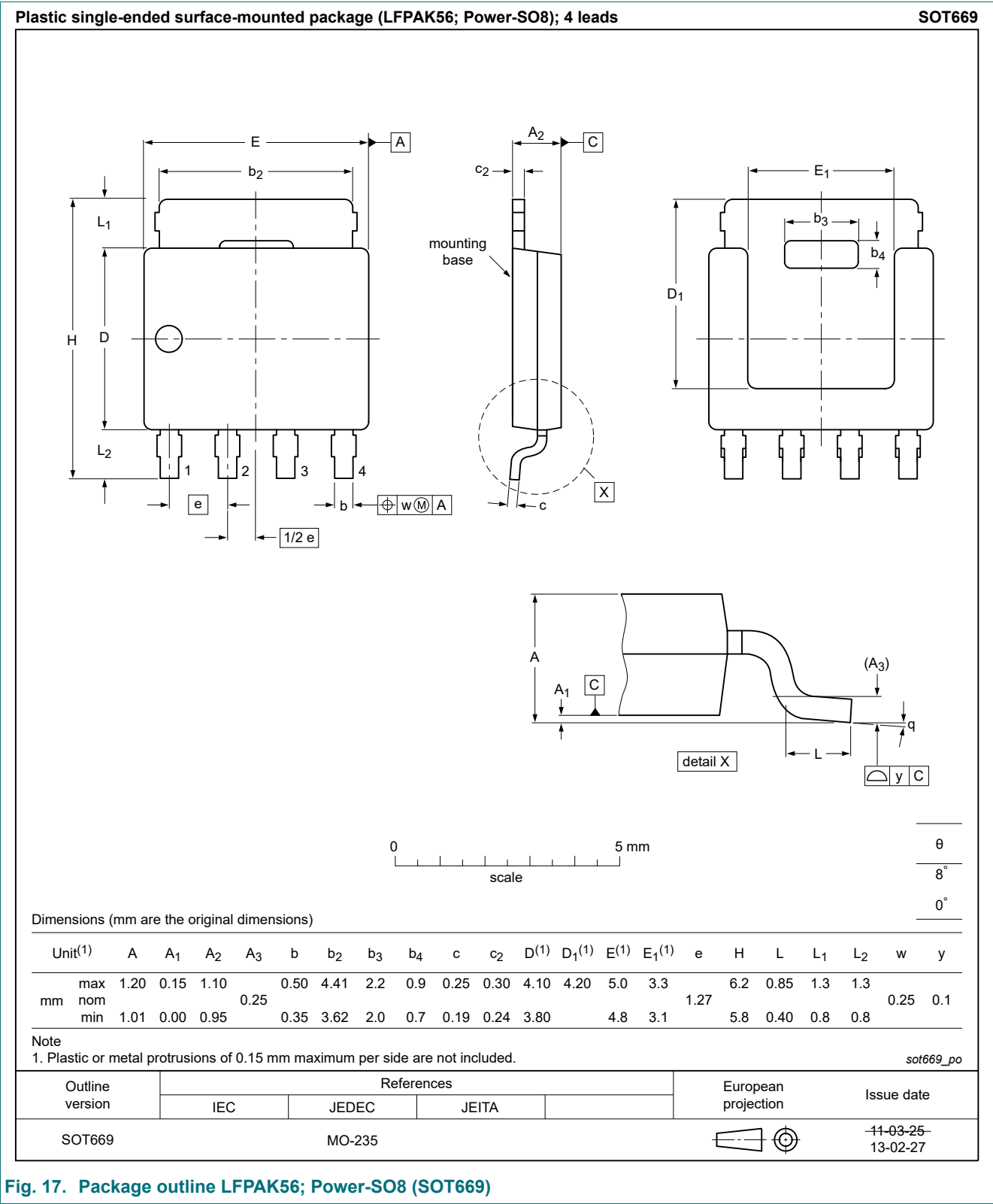


Fig. 17. Package outline LPAK56; Power-SO8 (SOT669)

12. Soldering

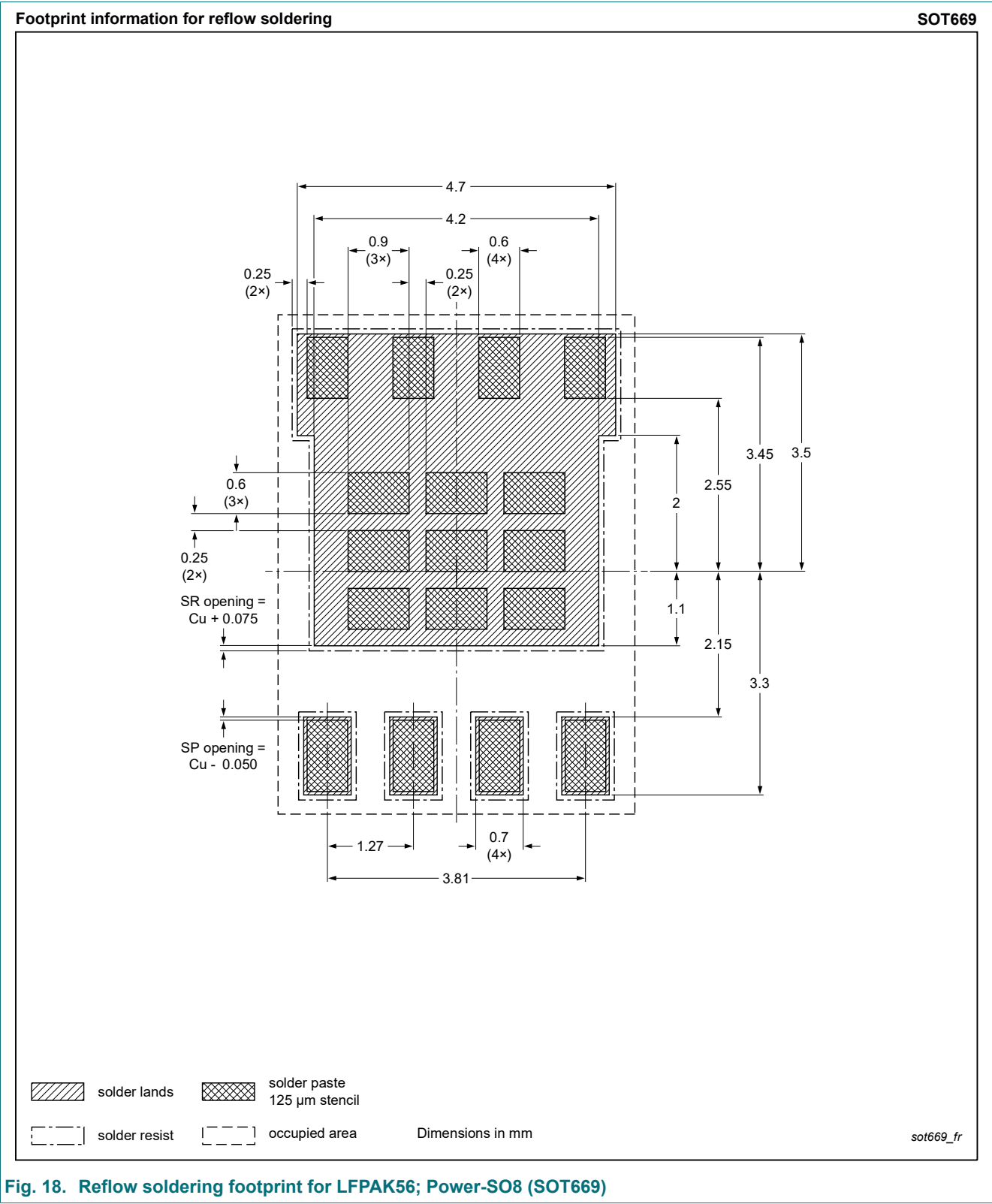


Fig. 18. Reflow soldering footprint for LPAK56; Power-SO8 (SOT669)

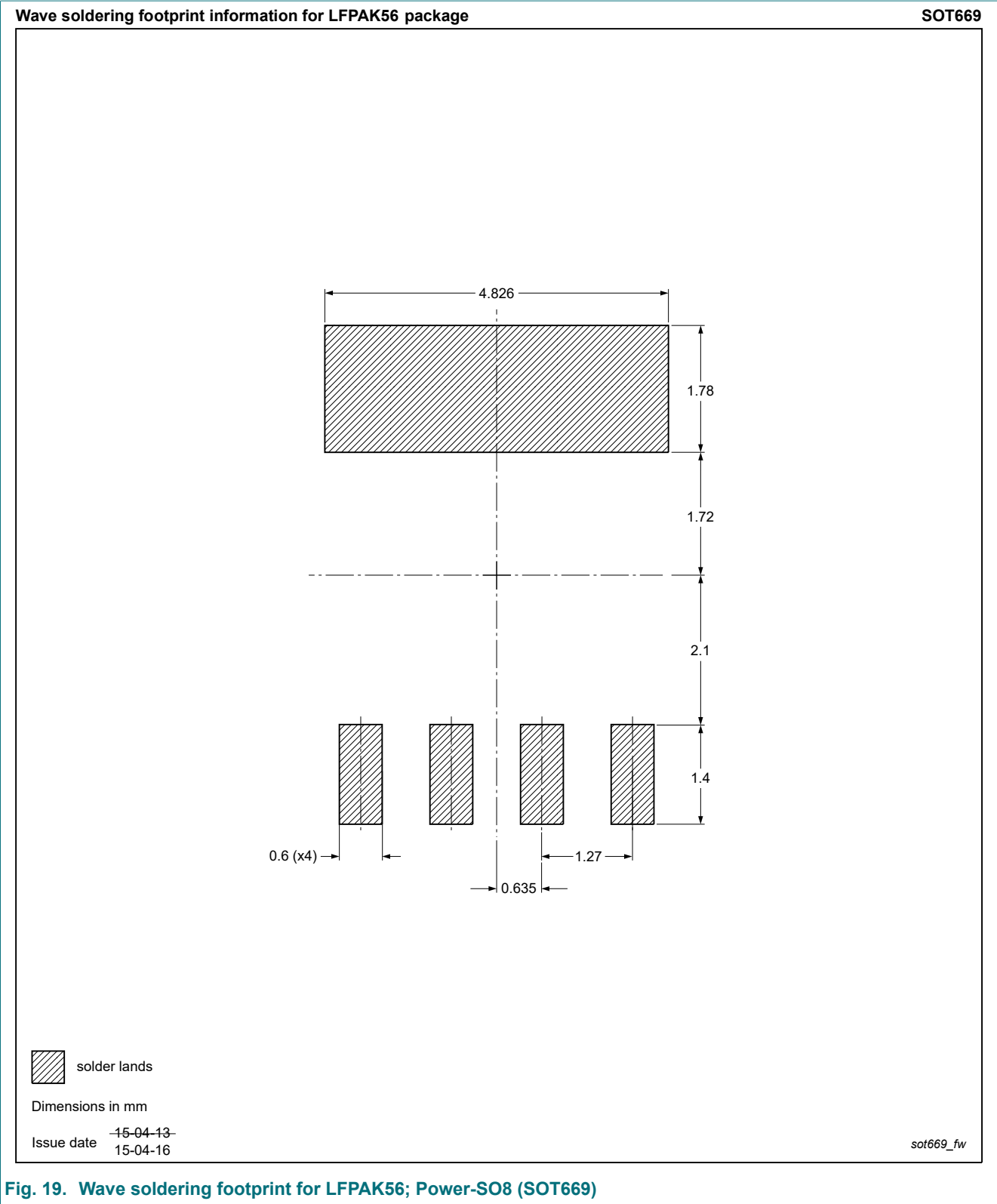


Fig. 19. Wave soldering footprint for LPAK56; Power-SO8 (SOT669)

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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